IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Todd O. Bolken

Serial No.: 10/791,192

Filed: March 2, 2004

For: TWO-STAGE TRANSFER MOLDING DEVICE TO ENCAPSULATE MMC

MODULE

Confirmation No.: 1966

Examiner: D. Zarneke

Group Art Unit: 2891

Attorney Docket No.: 2269-4794.4US (01-0185.04/US)

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FEE ADDRESSEE FOR RECEIPT OF PTO NOTICES RELATING TO MAINTENANCE FEES

Mail Stop ISSUE FEE Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

This letter is to specify that the FEE ADDRESSEE for this patent is:

MICRON TECHNOLOGY, INC.

Mail Stop 525 8000 South Federal Way Boise, Idaho 83707-0006

- The Customer Number for the Fee Addressee is 26809. 2.
- Any prior FEE ADDRESSEE for this patent is hereby revoked. 3.
- It is certified that the person whose signature appears below has the authority to 4. change the FEE ADDRESSEE for this patent.

Respectfully submitted,

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